

CARRIER PLATE REMOVING METHOD

ABSTRACT OF THE DISCLOSURE

There is provided a carrier plate removing method of removing a carrier plate from a workpiece disposed on a front surface of the carrier plate with a provisional bond layer interposed between the carrier plate and the workpiece. The carrier plate removing method includes a first holding step of holding the carrier plate and exposing the workpiece, a stepped portion forming step of forming a stepped portion in which an back surface side projects outward of a front surface side at an outer peripheral edge of the carrier plate, a second holding step of holding the workpiece and exposing the carrier plate, and a carrier plate removing step of removing the carrier plate from the workpiece by applying a force to the stepped portion and moving the carrier plate in a direction of being separated from the workpiece by a removing unit.

FIGURE 1B.